

RELIABILITY REPORT
FOR
MAX531BCSD+
PLASTIC ENCAPSULATED DEVICES

December 17, 2010

MAXIM INTEGRATED PRODUCTS

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Approved by
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Conclusion

The MAX531BCSD+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX531/MAX538/MAX539 are low-power, voltage- output, 12-bit digital-to-analog converters (DACs) specified for single +5V power-supply operation. The MAX531 can also be operated with $\pm 5V$ supplies. The MAX538/MAX539 draw only 140 μA , and the MAX531 (with internal reference) draws only 260 μA . The MAX538/MAX539 come in 8-pin DIP and SO packages, while the MAX531 comes in 14-pin DIP and SO packages. All parts have been trimmed for offset voltage, gain, and linearity, so no further adjustment is necessary. The MAX538's buffer is fixed at a gain of +1 and the MAX539's buffer at a gain of +2. The MAX531's internal op amp may be configured for a gain of +1 or +2, as well as for unipolar or bipolar output voltages. The MAX531 can also be used as a four-quadrant multiplier without external resistors or op amps. For parallel data inputs, see the MAX530 data sheet.

II. Manufacturing Information

A. Description/Function:	+5V, Low-Power, Voltage-Output, Serial 12-Bit DACs
B. Process:	S3
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Malaysia, Philippines, Thailand
F. Date of Initial Production:	Pre 1997

III. Packaging Information

A. Package Type:	14-pin SOIC (N)
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-0401-0333
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	120°C/W
K. Single Layer Theta Jc:	37°C/W
L. Multi Layer Theta Ja:	N/A
M. Multi Layer Theta Jc:	N/A

IV. Die Information

A. Dimensions:	80 X 120 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	3.0 microns (as drawn)
F. Minimum Metal Spacing:	3.0 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Don Lipps (Manager, Reliability Engineering) Bryan Preeshl (Vice President of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 160 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 6.9 \times 10^{-9}$$
$$\lambda = 6.9 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the S3 Process results in a FIT Rate of 0.04 @ 25C and 0.69 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (lot NXMAGA406A D/C 0247)

The DA44 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

Table 1
Reliability Evaluation Test Results

MAX531BCSD+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C	DC Parameters	80	0	NXMBEA405B, D/C 0236
	Biased	& functionality	80	0	XXMBCD038B, D/C 9724
	Time = 192 hrs.				

Note 1: Life Test Data may represent plastic DIP qualification lots.